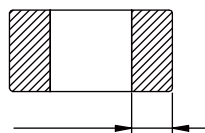


SMD EMI Suppression Ferrite Bead Size 0402

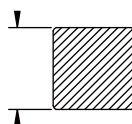


- Monolithic inorganic material construction.
 - Closed magnetic circuit avoids crosstalk.
 - Suitable for reflow soldering.
 - Available in various sizes.
 - Quantity: 10000pcs
-
- Data lines and low power lines
 - Connection between digital and analog circuit

Dimensions: [mm]

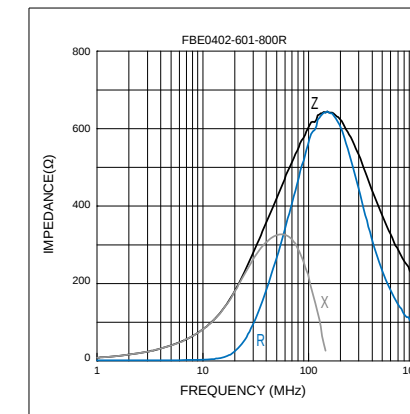
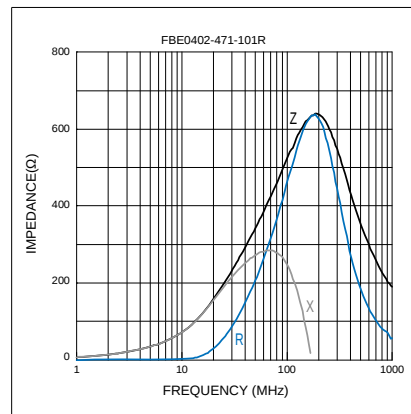
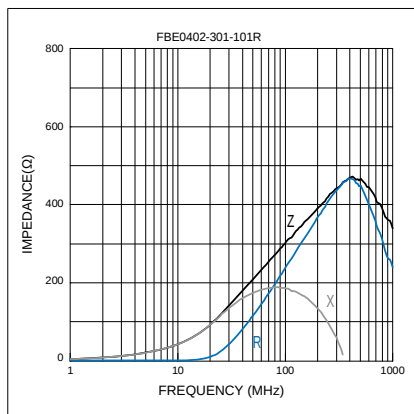
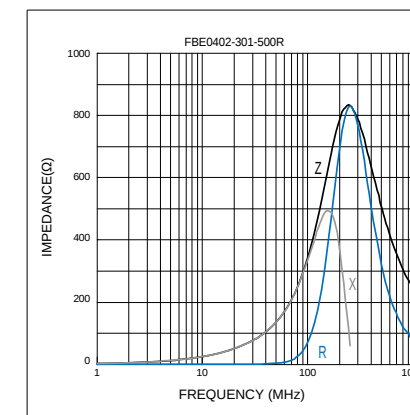
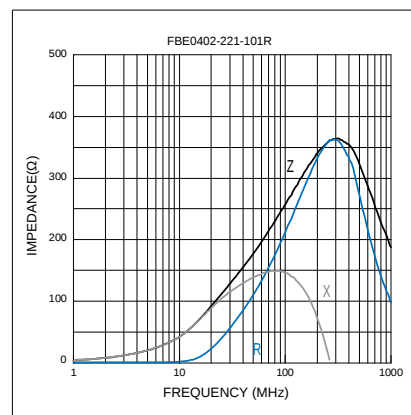
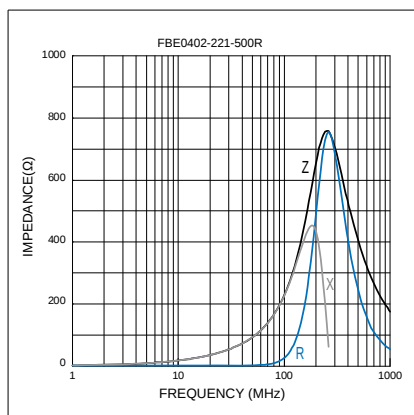
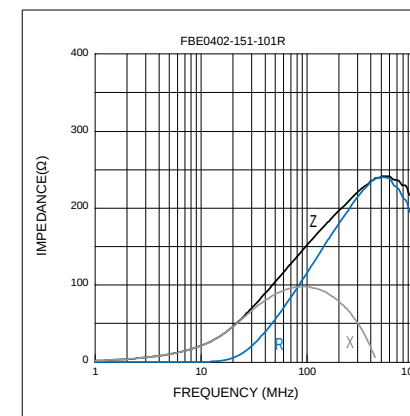
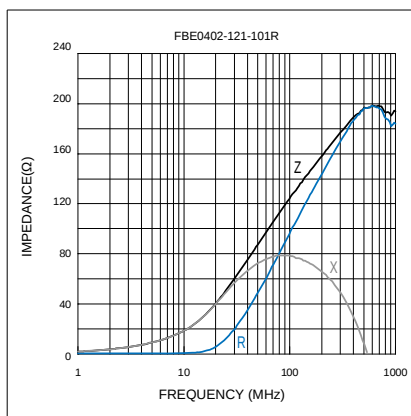
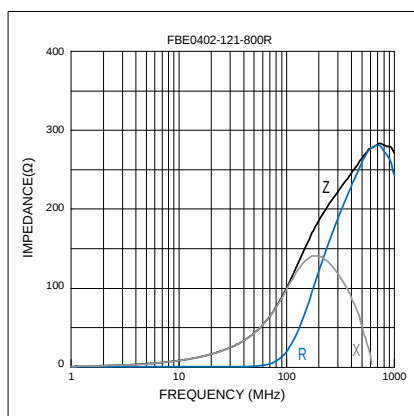
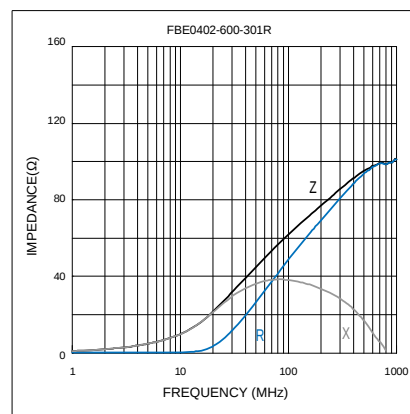
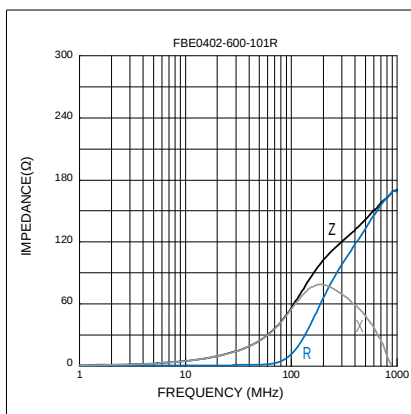
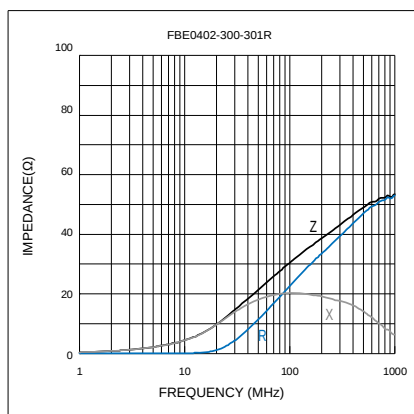


Land Pattern: [mm]

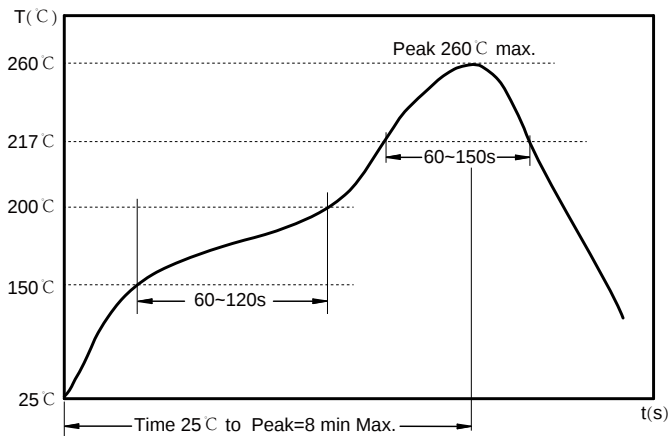


Electrical Properties:

Impedance & Frequency Characteristics:



Soldering Reflow:



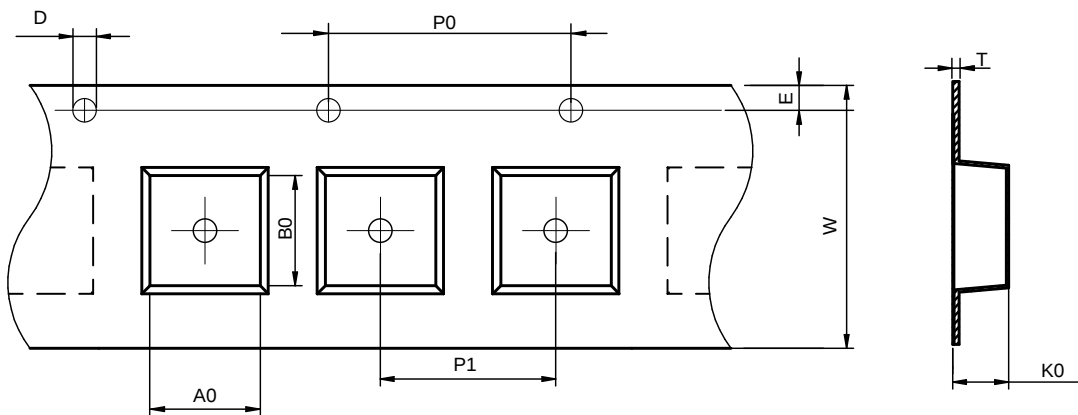
Preheat condition: 150 ~200 °C / 60~120 sec.

Allowed time above 217 °C: 60~150 sec.

Max temperature: 260 °C.

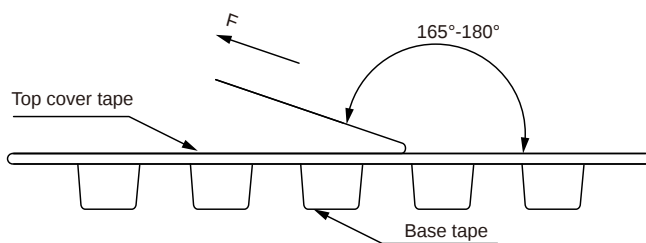
Packaging Information:

Tape Dimension:



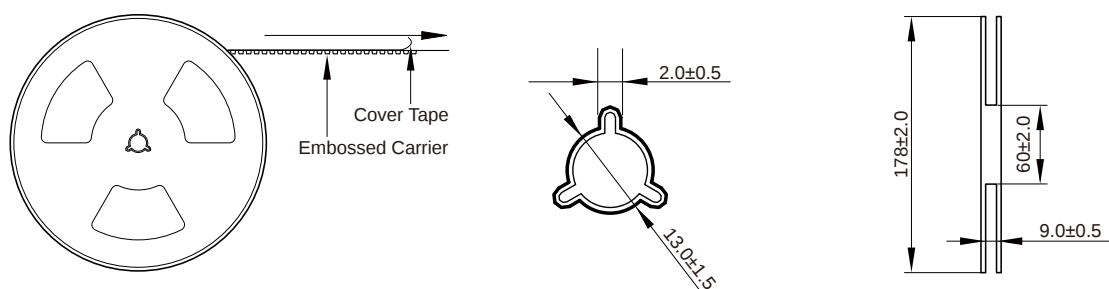
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
FBE0402	0.62±0.03	1.12±0.03	1.5±0.1	4.0±0.1	4.0±0.1	8.0±0.3	0.60±0.03	1.75±0.1	0.60±0.03

Peel force of top cover tape:

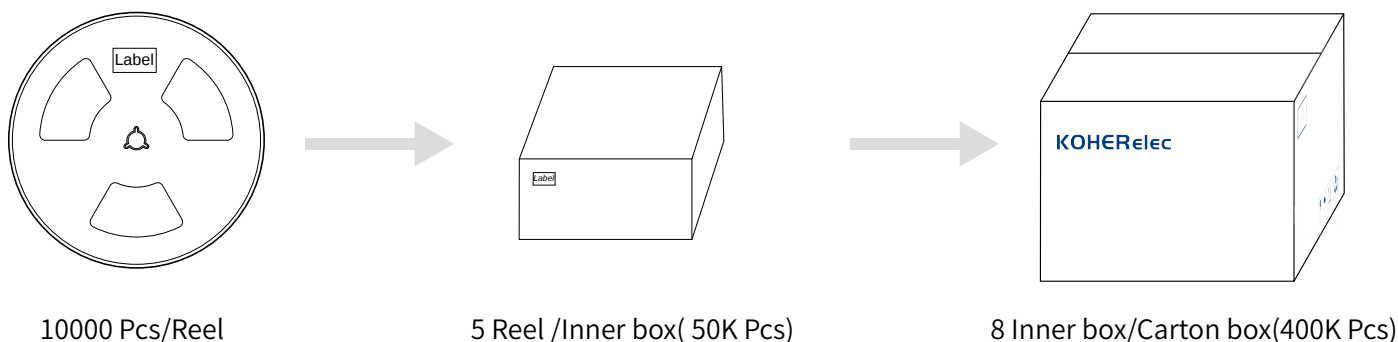


The peel force of top cover tape shall be between 0.14 to 0.58 N

Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.